Vincotech

30-P2126PA150M7-L280F79Y
30-F2126PA150M7-L280F79
datasheet

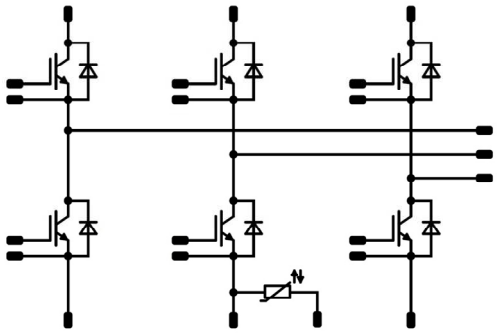
flow PACK 2 — **1200 V / 150 A**

Features
- IGBT M7 technology with low V_{CEsat} and improved EMC improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Builtin NTC

flow 2 17 mm housing

Solder pin | Press-fit pin

Schematic



Target applications
- Industrial Drives
- Power Supply
- UPS

Types
- 30-F2126PA150M7-L280F79
- 30-P2126PA150M7-L280F79Y

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	140	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	300	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	252	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	T_j = T_{jmax} T_s = 80°C	122	A
Repetitive peak forward current	I_{FRM}		300	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80°C	186	W
Maximum Junction Temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage t_p = 2 s	4000	V
Creepage distance			min. 12,7	mm
Clearance			min. 12,7	mm
Comparative Tracking Index	CTI		> 200	

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		150	25 125 150		1,55 1,75 1,80	2,05	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			160	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							3		Ω
Input capacitance	C_{ies}		0	10		25		30000		pF
Output capacitance	C_{oes}							880		
Reverse transfer capacitance	C_{res}							320		
Gate charge	Q_g		15	600	150	25		1000		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material λ = 3,4 W/mK						0,38		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 1 Ω R_{gon} = 1 Ω	±15	600	150	25 125 150		269 290 292		ns
Rise time	t_r					25 125 150		60 73 77		
Turn-off delay time	$t_{d(off)}$					25 125 150		231 267 273		
Fall time	t_f					25 125 150		73 90 96		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 15,5 µC Q_{rFWD} = 23,4 µC Q_{rFWD} = 26,1 µC				25 125 150		16,785 22,035 23,734		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		9,701 12,816 13,803		

Characteristic Values

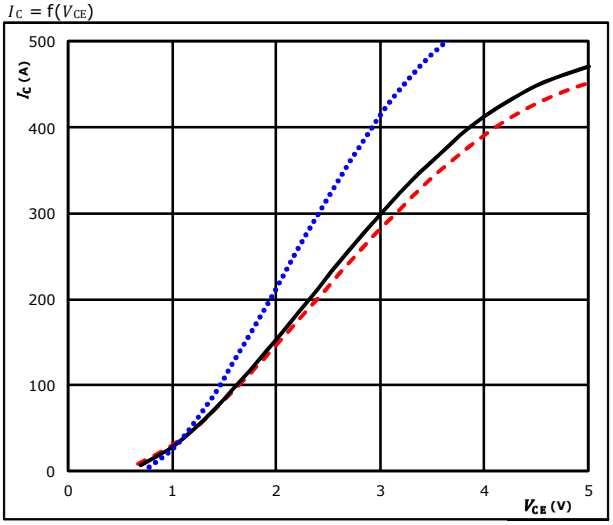
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				150	25 125 150		1,60 1,65 1,65	2,1	V
Reverse leakage current	I_r			1200		25			90	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material λ = 3,4 W/mK						0,51		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 1603 A/µs di/dt = 1435 A/µs di/dt = 1541 A/µs	±15	600	150	25 125 150		78 83 85		A
Reverse recovery time	t_{rr}					25 125 150		385 531 590		ns
Recovered charge	Q_r					25 125 150		15,528 23,396 26,076		µC
Reverse recovered energy	E_{rec}					25 125 150		5,492 8,659 9,652		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		490 293 264		A/µs
Thermistor										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1486 Ω				100	-12		+14	%
Power dissipation	P					25		200		mW
Power dissipation constant						25		2		mW/K
B-value	$B_{(25/50)}$	Tol. ±3%				25		3950		K
B-value	$B_{(25/100)}$	Tol. ±3%				25		3998		K
Vincotech NTC Reference									B	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

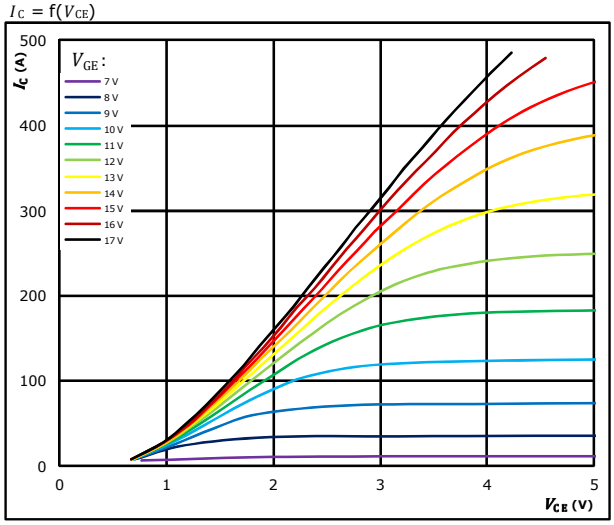


t_p =	250	µs		25 °C	
V_{GE} =	15	V	T_j:	125 °C	
				150 °C	

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

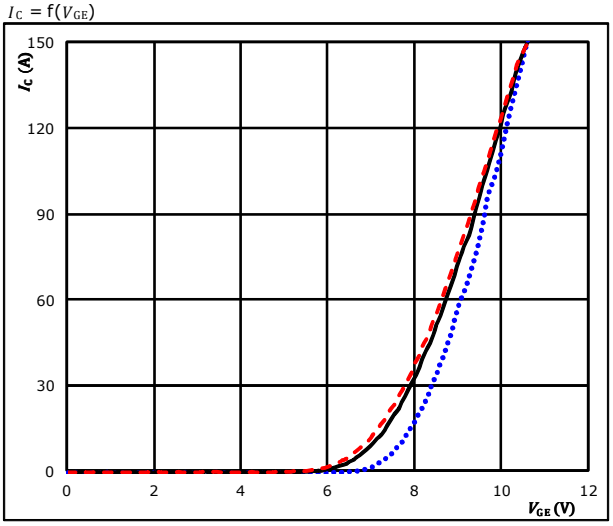


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

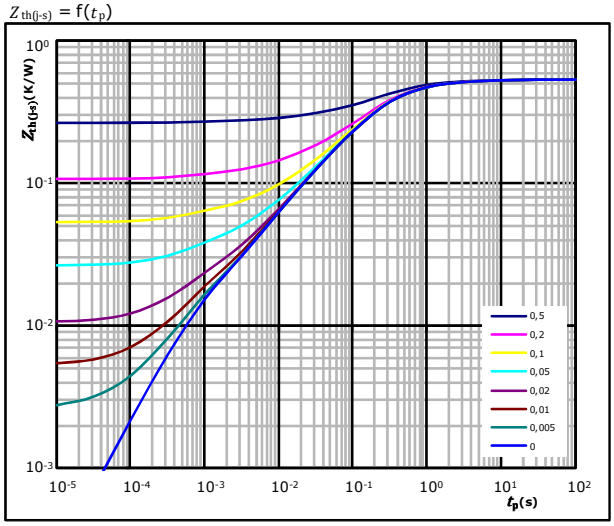


t_p =	100	µs		25 °C	
V_{CE} =	10	V	T_j:	125 °C	
				150 °C	

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



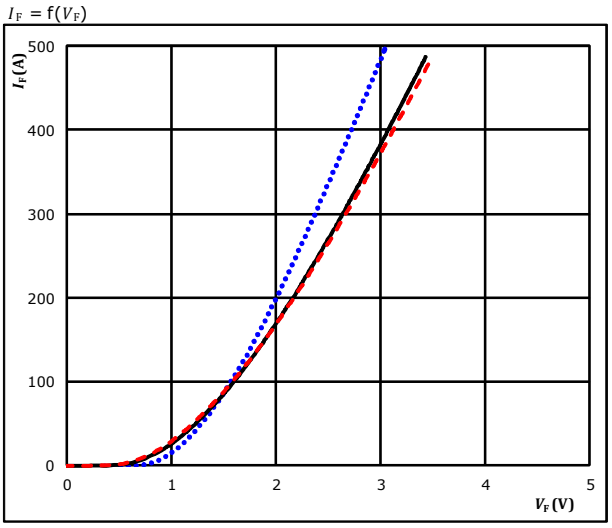
D =	t_p / T	
$R_{th(j-s)}$ =	0,38	K/W

IGBT thermal model values

R (K/W)	τ (s)
4,47E-02	2,80E+00
9,73E-02	5,59E-01
2,47E-01	1,59E-01
3,88E-02	2,12E-02
1,13E-02	5,12E-03
1,42E-02	6,59E-04
1,48E-02	4,14E-04

Inverter Diode Characteristics

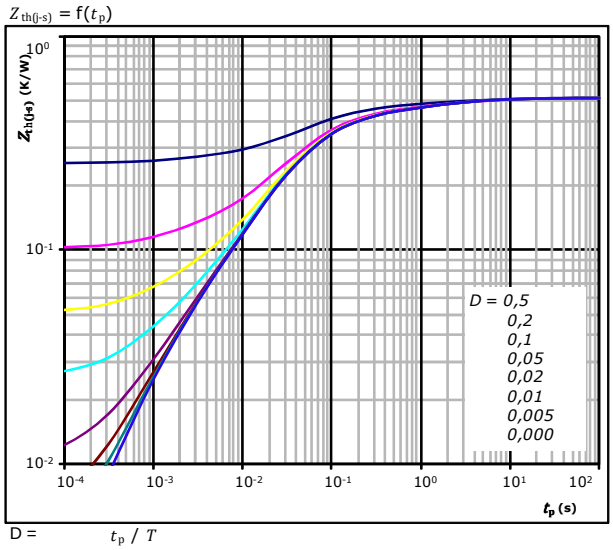
Typical forward characteristics **FWD**



t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

Transient thermal impedance as a function of pulse width **FWD**



D = t_p / T

$R_{th(j-s)}$ = 0,51 K/W

FWD thermal model values

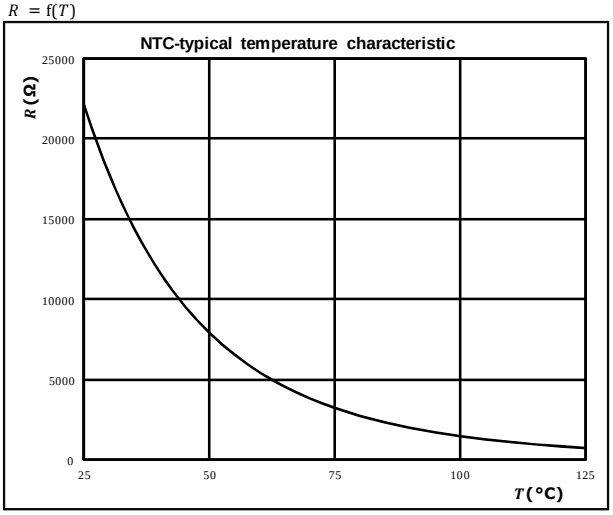
R (K/W)	τ (s)
3,20E-02	5,81E+00
5,21E-02	1,13E+00
1,20E-01	1,65E-01
2,21E-01	4,07E-02
6,16E-02	1,11E-02
2,49E-02	1,34E-03

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

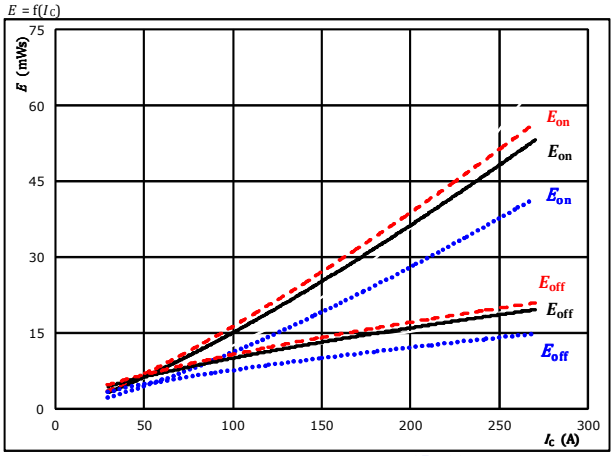


Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



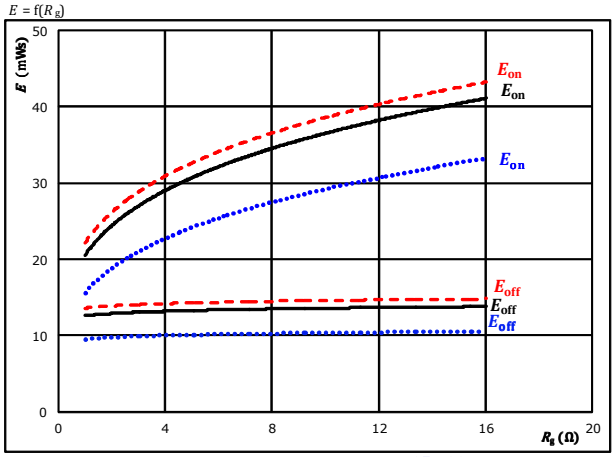
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
R_{gon} =	1	Ω		150 °C	– – –
R_{goff} =	1	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



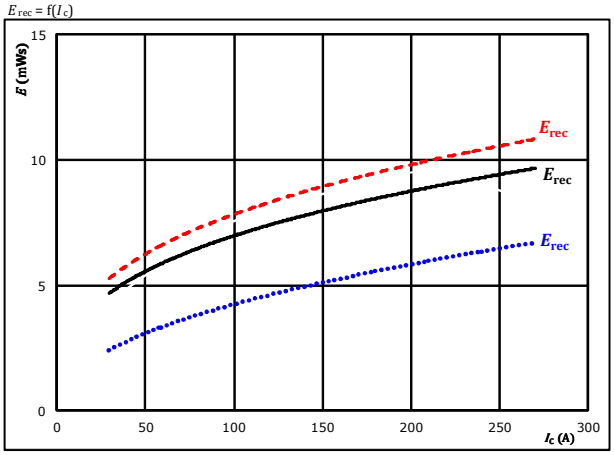
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
I_C =	150	A		150 °C	– – –

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



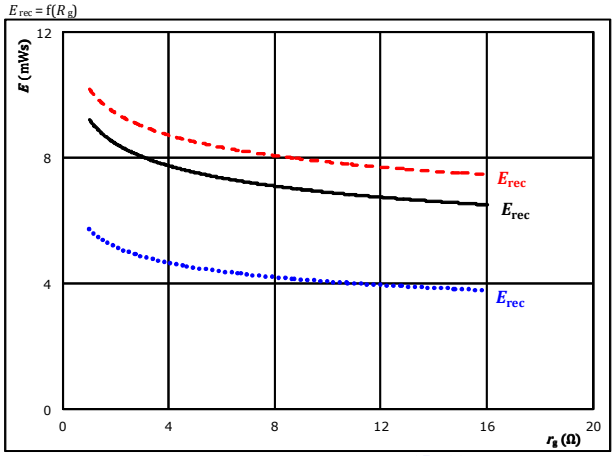
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
R_{gon} =	1	Ω		150 °C	– – –

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

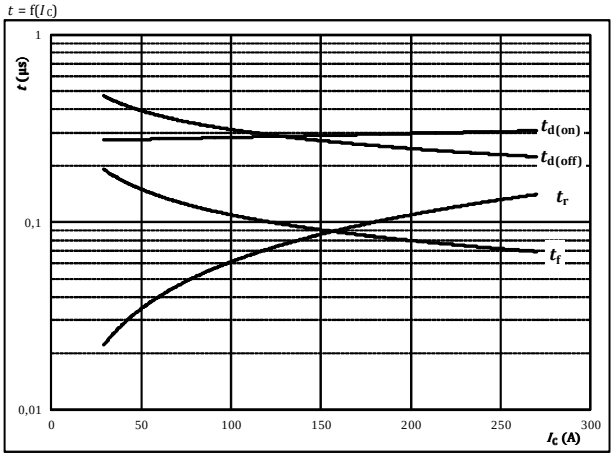
V_{CE} =	600	V	T_J:	25 °C	·····
V_{GE} =	±15	V		125 °C	———
I_C =	150	A		150 °C	– – –

Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



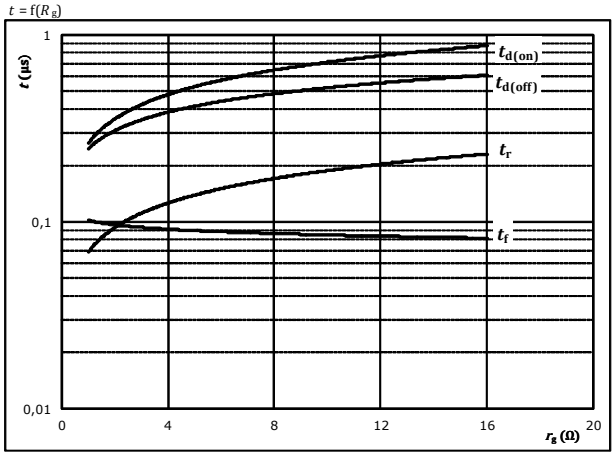
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	1	Ω
R_{goff} =	1	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



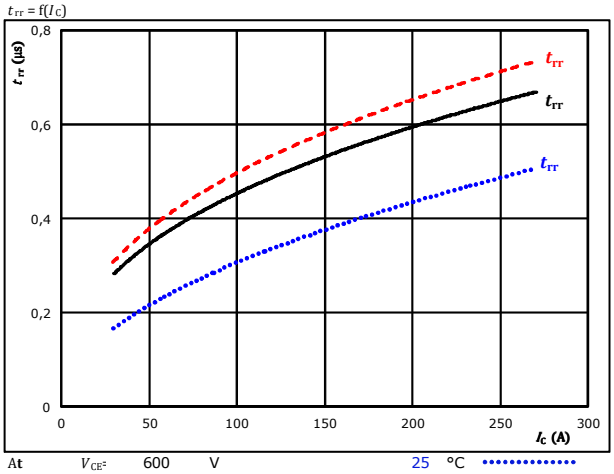
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	150	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

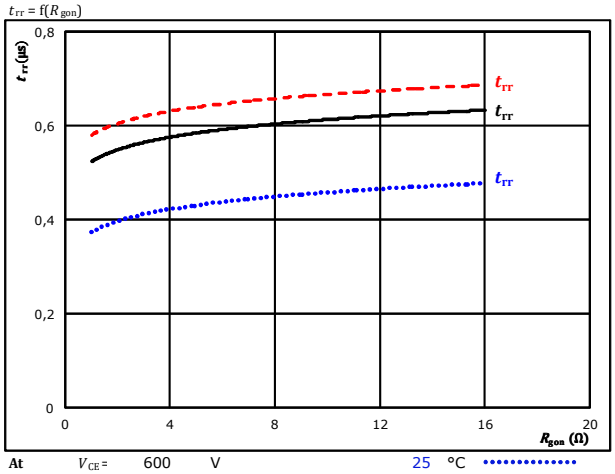


At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
R_{gon} =	1	Ω		150	°C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



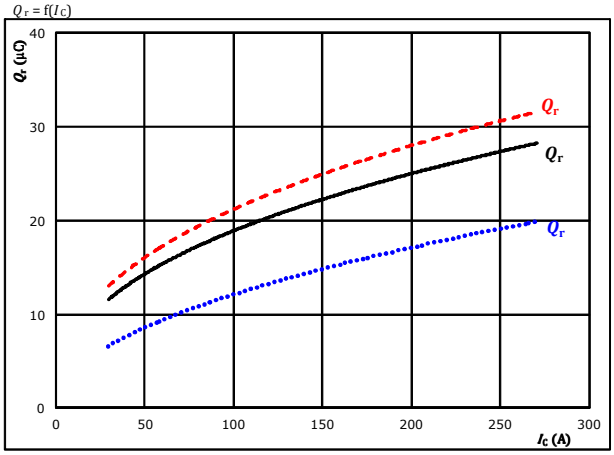
At					
V_{CE} =	600	V		25	°C
V_{GE} =	±15	V	T_j:	125	°C
I_C =	150	A		150	°C

Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

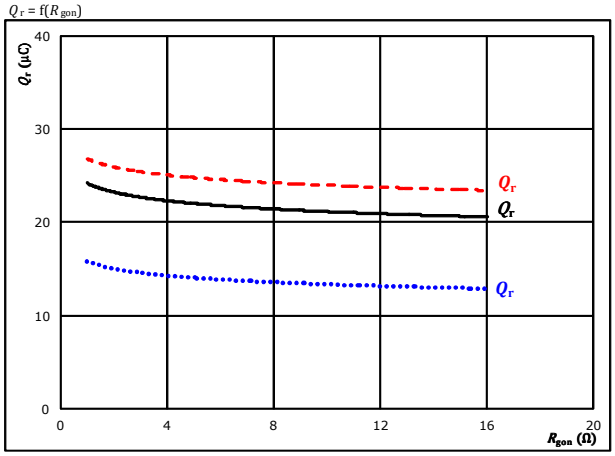


At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	R_{gon} =	1	Ω		150 °C	

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

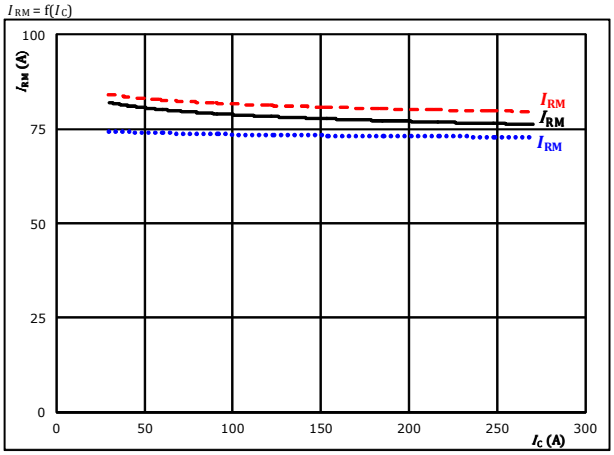


At						
	V_{CE}=	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	I_C=	150	A		150 °C	

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

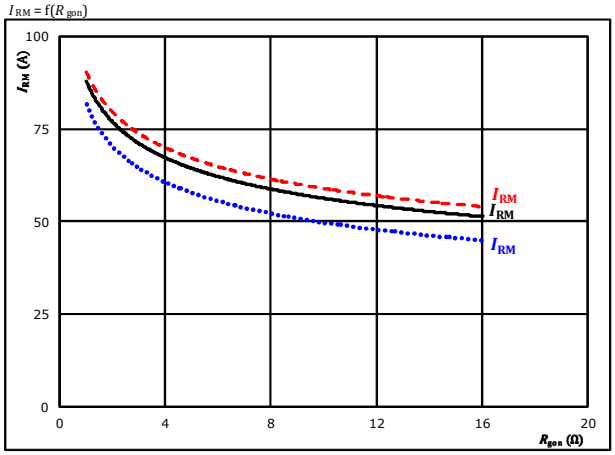


At						
	V_{CE}:	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	R_{gon} =	1	Ω		150 °C	

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



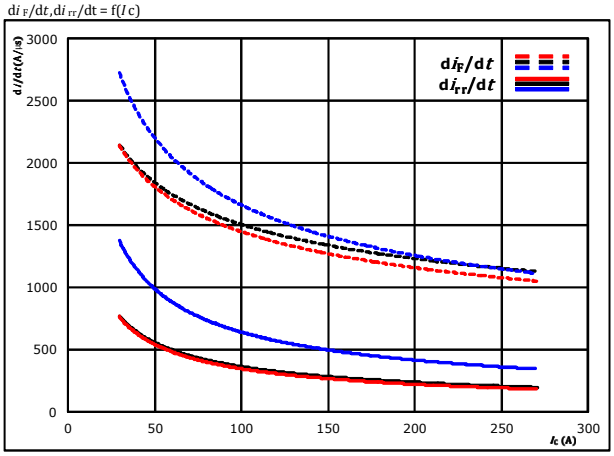
At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	125 °C	
	I_C =	150	A		150 °C	

Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

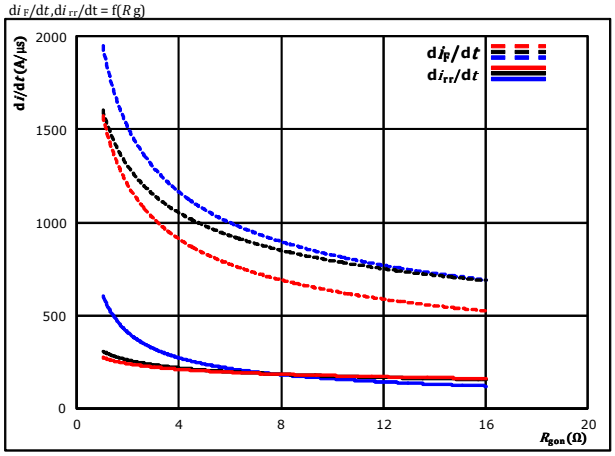


At						
V_{CE} =	600	V		25	°C	
V_{GE} =	±15	V	T_j:	125	°C	
R_{gon} =	1	Ω		150	°C	

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_g)$

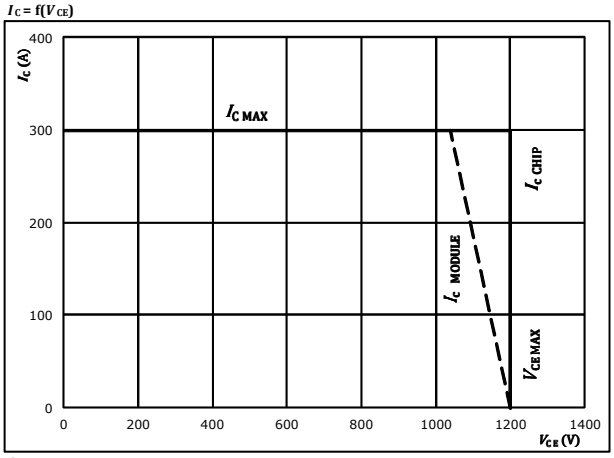


At						
V_{CE} =	600	V		25	°C	
V_{GE} =	±15	V	T_j:	125	°C	
I_C =	150	A		150	°C	

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	1	Ω
R_{goff} =	1	Ω

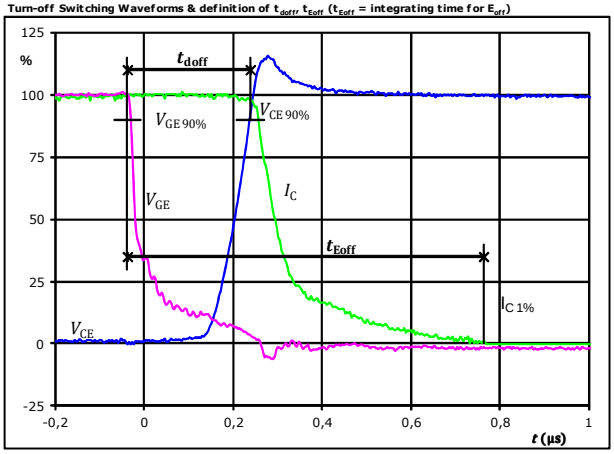
Switching Definitions

General conditions

T_j	=	**125 °C**
R_{gon}	=	**1 Ω**
R_{goff}	=	**1 Ω**

figure 1. **IGBT**

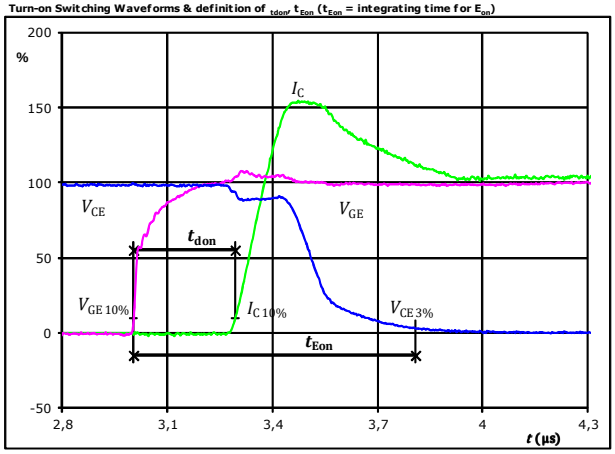
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	150	A
t_{doff} =	0,267	µs
t_{Eoff} =	0,801	µs

figure 2. **IGBT**

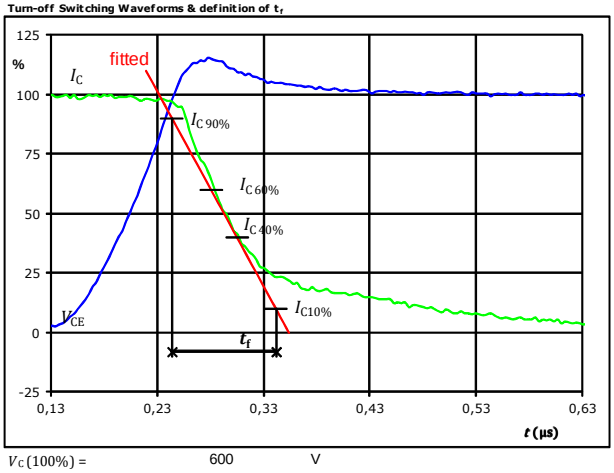
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	150	A
t_{don} =	0,290	µs
t_{Eon} =	0,805	µs

figure 3. **IGBT**

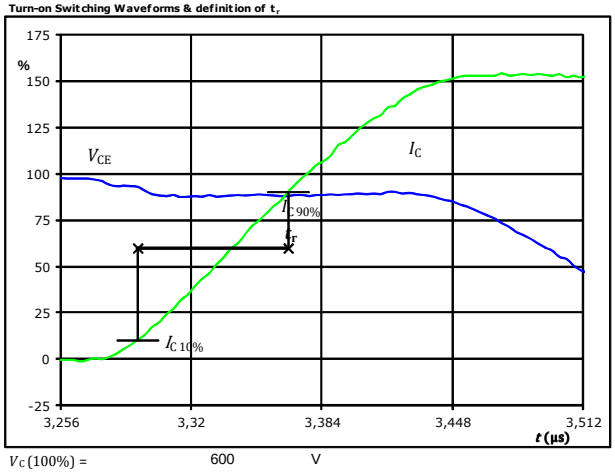
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	150	A
t_f =	0,090	µs

figure 4. **IGBT**

Turn-on Switching Waveforms & definition of t_r

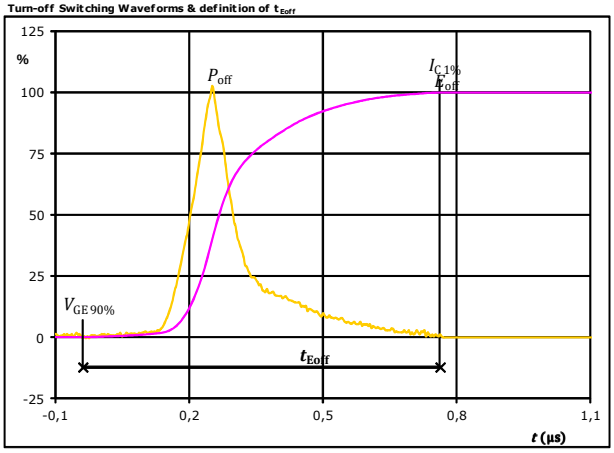


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	150	A
t_r =	0,073	µs

Switching Characteristics

figure 5. **IGBT**

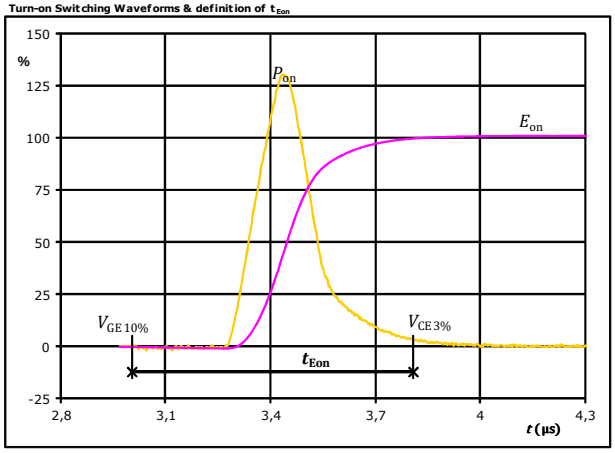
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	90,17	kW
$E_{off}(100\%)$ =	12,82	mJ
t_{Eoff} =	0,80	µs

figure 6. **IGBT**

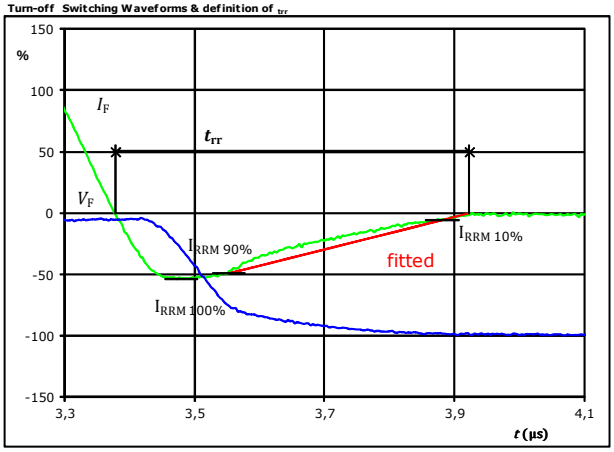
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	90,17	kW
$E_{on}(100\%)$ =	22,03	mJ
t_{Eon} =	0,80	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

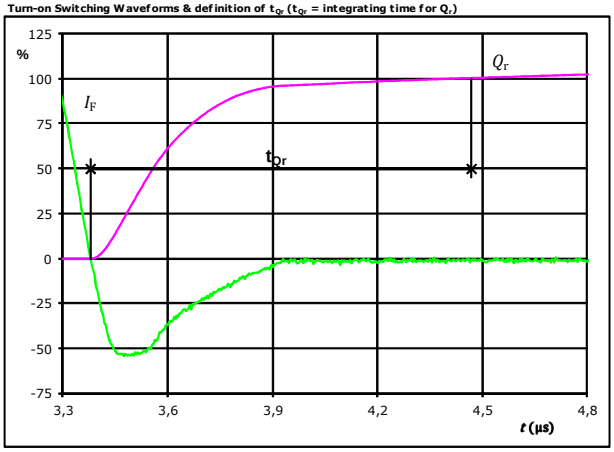


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	150	A
$I_{RRM}(100\%)$ =	-83	A
t_{rr} =	0,531	µs

Switching Characteristics

figure 8. **FWD**

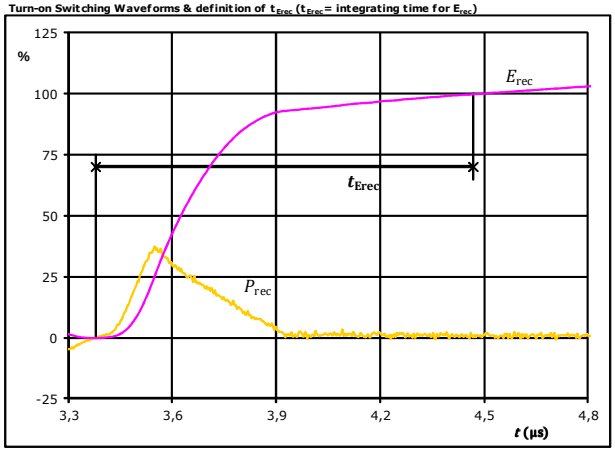
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	150	A
Q_r (100%) =	23,40	µC
t_{Qr} =	1,09	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	90,17	kW
E_{rec} (100%) =	8,66	mJ
t_{Erec} =	1,09	µs

Ordering Code & Marking

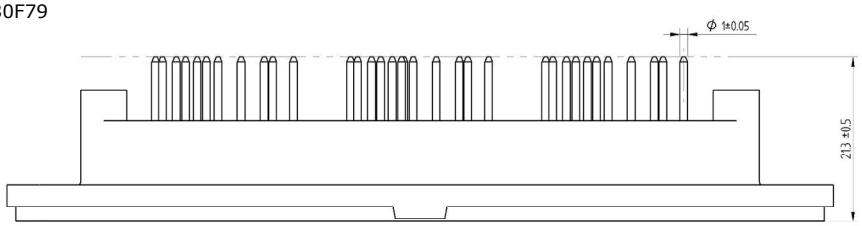
Version	Ordering Code
without thermal paste 17mm housing with Solder pins	30-F2126PA150M7-L280F79
with thermal paste 17mm housing with Solder pins	30-F2126PA150M7-L280F79-/3/
without thermal paste 17mm housing with Press-fit pins	30-P2126PA150M7-L280F79Y
with thermal paste 17mm housing with Press-fit pins	30-P2126PA150M7-L280F79Y-/3/

	Name		Date code	UL & VIN	Lot	Serial
Text	N-NNNNNNNNNNNNN-TTTTTTV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTVV	LLLLL	SSSS	WWYY		

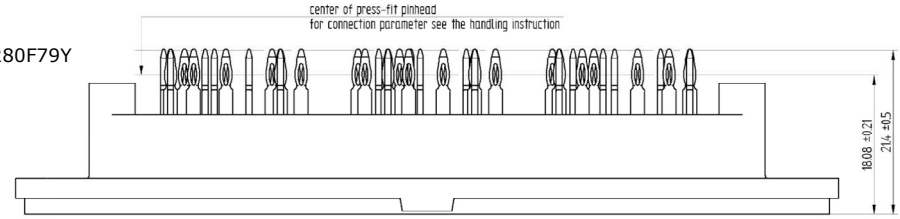
Outline

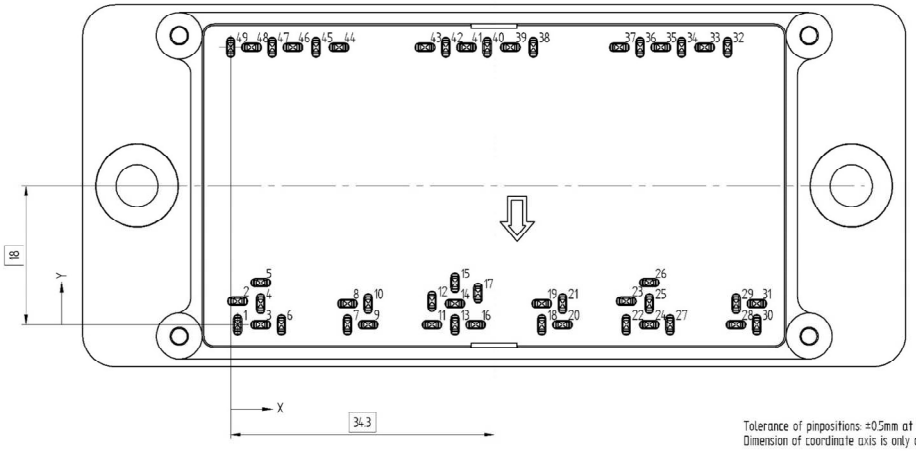
Pin table [mm]			
Pin	X	Y	Function
1	0,9	0	S11
2	0,9	3	G11
3	3,9	0	DC-1
4	3,9	2,7	DC-1
5	3,9	5,4	DC-1
6	6,6	0	DC-1
7	15,2	0	DC+1
8	15,2	2,7	DC+1
9	17,9	0	DC+1
10	17,9	2,7	DC+1
11	26,2	0	S13
12	26,2	3	G13
13	29,2	0	DC-2
14	29,2	2,7	DC-2
15	29,2	5,4	DC-2
16	31,9	0	DC-2
17	32,2	4,05	NTC
18	40,5	0	DC+2
19	40,5	2,7	DC+2
20	43,2	0	DC+2
21	43,2	2,7	DC+2
22	51,5	0	S15
23	51,5	3	G15
24	54,5	0	DC-3
25	54,5	2,7	DC-3
26	54,5	5,4	DC-3
27	57,2	0	DC-3
28	65,8	0	DC+3
29	65,8	2,7	DC+3
30	68,5	0	DC+3
31	68,5	2,7	DC+3
32	64,7	36	G16
33	61,7	36	S16
34	58,7	36	PH3
35	56	36	PH3
36	53,3	36	PH3
37	50,6	36	PH3
38	39,4	36	G14
39	36,4	36	S14
40	33,4	36	PH2
41	30,7	36	PH2
42	28	36	PH2
43	25,3	36	PH2
44	14,1	36	G12
45	11,1	36	S12
46	8,1	36	PH1
47	5,4	36	PH1
48	2,7	36	PH1
49	0	36	PH1

L280F79



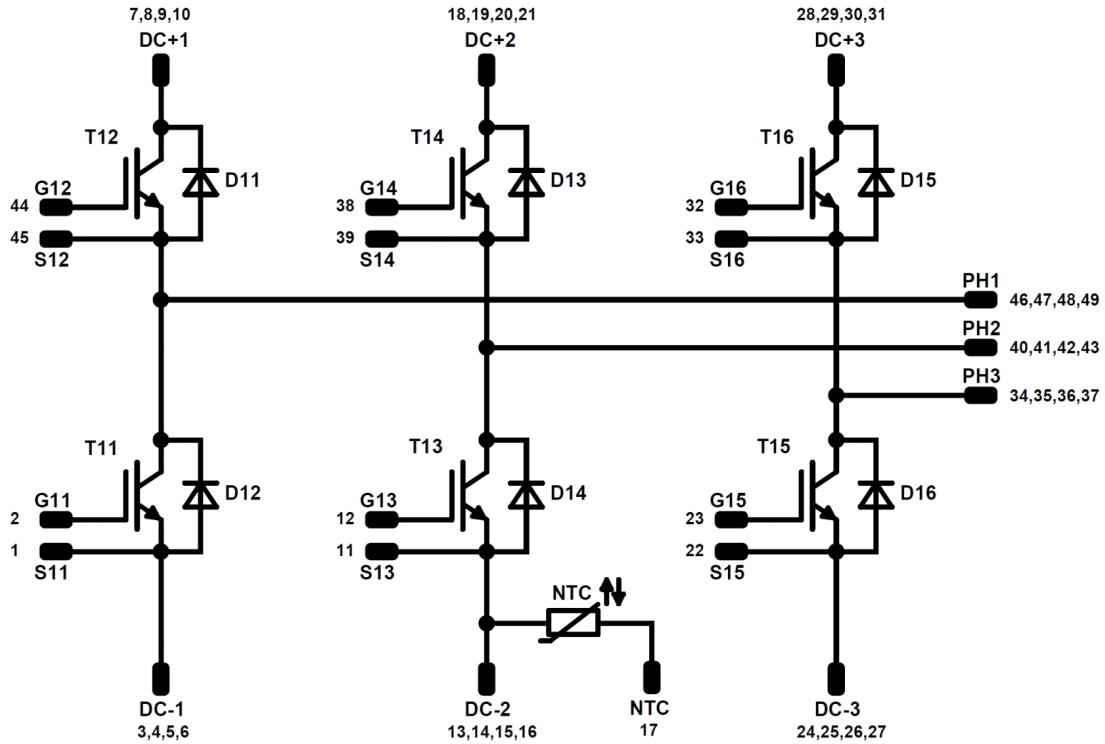
L280F79Y





Tolerance of pinpositions: ±0.5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11 , T12 , T13 , T14 , T15 , T16	IGBT	1200 V	150 A	Inverter Switch	
D11 , D12 , D13 , D14 , D15 , D16	FWD	1200 V	150 A	Inverter Diode	
NTC	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 36	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 2 packages see vincotech.com website.

Package data
Package data for *flow* 2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
30-x2126PA150M7-L280F79x-D3-14	07 Mar. 2019	flow2 frame modification Added solder pin variant	1,15